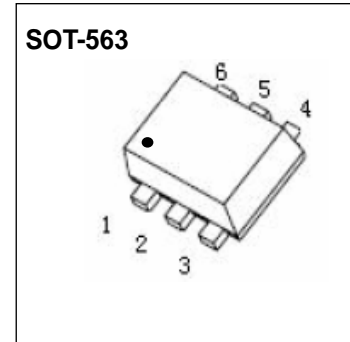


## Plastic-Encapsulate MOSFETS

### Dual P-Channel Power MOSFET

$V_{(BR)DSS}$	$R_{DS(on)MAX}$	$I_D$
- 20V	520m $\Omega$ @ - 4.5V	- 0.66A
	700m $\Omega$ @ - 2.5V	
	950m $\Omega$ (TYP) @ - 1.8V	



### GENERAL DESCRIPTION

This Dual P- Channel MOSFET has been designed using advanced Power Trench process to optimize the  $R_{DS(ON)}$ .

Including two P-ch FTK3139PP MOSFET (independently) in a package.

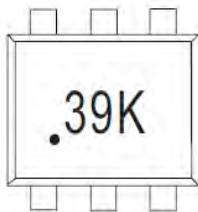
### FEATURE

- High- Side Switching
- Low On- Resistance
- Low Threshold
- Fast Switching Speed

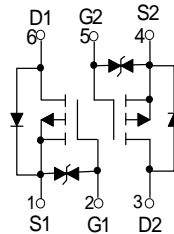
### APPLICATION

- Drivers: Relays, Solenoids, Lamps, Hammers, Displays, Memories
- Battery Operated Systems
- Power Supply Converter Circuits
- Load/Power Switching Cell Phones, Pages

### MARKING



### Equivalent Circuit



### Maximum ratings ( $T_a=25^\circ\text{C}$ unless otherwise noted)

Parameter	Symbol	Value	Unit
Drain- Source voltage	$V_{DSS}$	- 20	V
Typical Gate- Source Voltage	$V_{GS}$	$\pm 12$	
Drain Current- Continuous	$I_{D(DC)}$	- 0.66	A
Drain Current - Pulsed(note1)	$I_{DM(pulse)}$	- 2.64	
Power Dissipation (note 2)	$P_D$	150	mW
Thermal Resistance from Junction to Ambient	$R_{\theta JA}$	833	$^\circ\text{C}/\text{W}$
Storage Temperature	$T_j$	150	$^\circ\text{C}$
Junction Temperature	$T_{stg}$	- 55~ +150	



## MOSFET ELECTRICAL CHARACTERISTICS

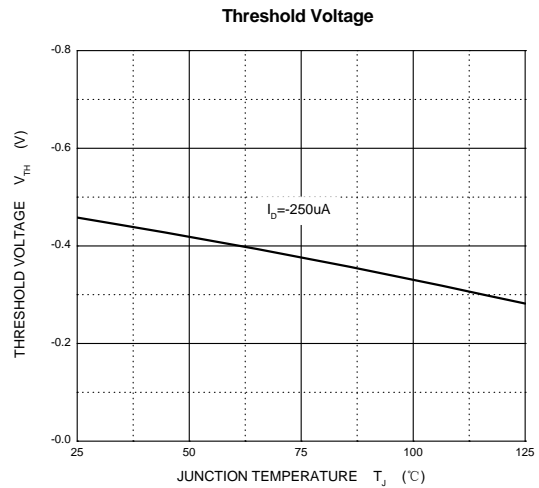
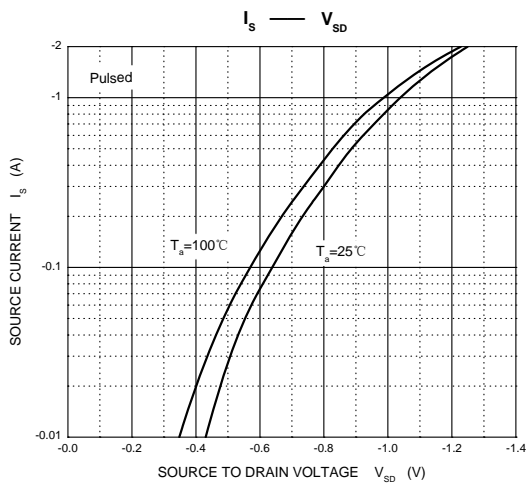
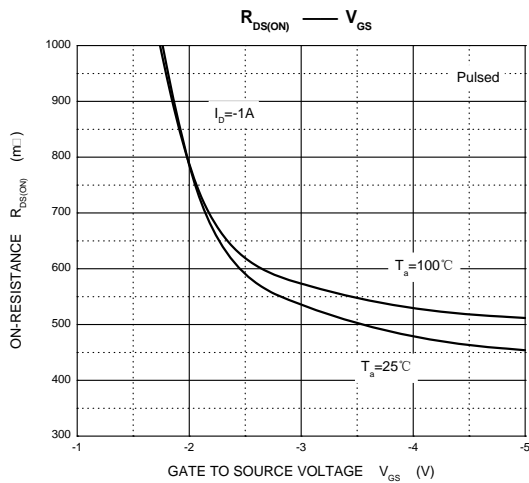
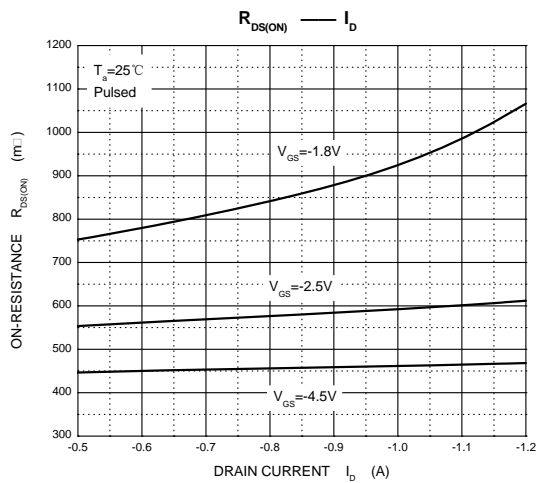
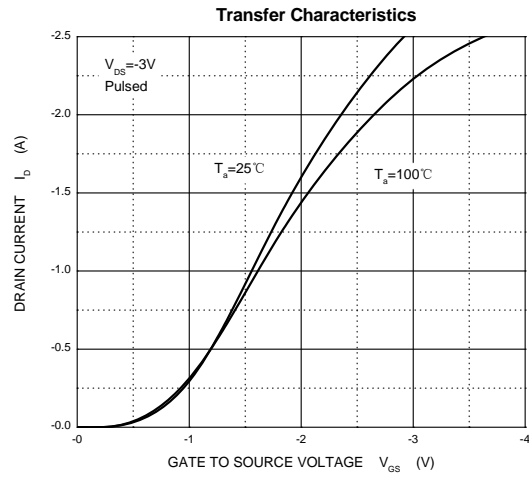
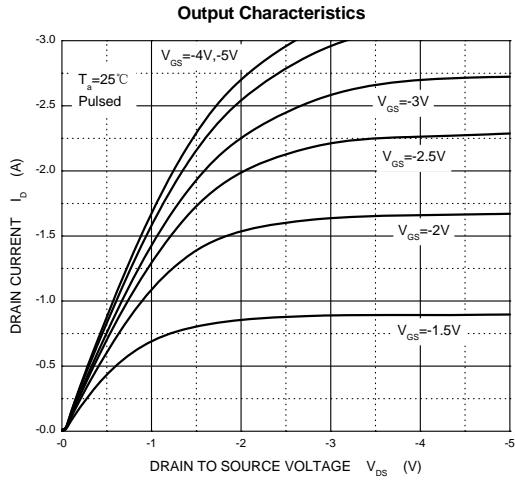
T<sub>a</sub>=25°C unless otherwise specified

Parameter	Symbol	Test Condition	Min	Typ	Max	Unit
<b>On/Off States</b>						
Drain-Source Breakdown Voltage	V <sub>(BR)DSS</sub>	V <sub>GS</sub> = 0V, I <sub>b</sub> = -250μA	-20			V
Gate-Threshold Voltage(note 3)	V <sub>GS(th)</sub>	V <sub>DS</sub> = V <sub>GS</sub> , I <sub>b</sub> = -250μA	-0.35		-1.1	V
Gate-Body Leakage Current	I <sub>GSS</sub>	V <sub>DS</sub> = 0V, V <sub>GS</sub> = ±10V			±20	μA
Zero Gate Voltage Drain Current	I <sub>DSS</sub>	V <sub>DS</sub> = -20V, V <sub>GS</sub> = 0V			-1	μA
Drain-Source On-State Resistance(note 3)	R <sub>DS(on)</sub>	V <sub>GS</sub> = -4.5V, I <sub>D</sub> = -1A		450	520	mΩ
		V <sub>GS</sub> = -2.5V, I <sub>D</sub> = -800mA		575	700	
		V <sub>GS</sub> = -1.8V, I <sub>D</sub> = -500mA		950		
Forward Transconductance	g <sub>FS</sub>	V <sub>DS</sub> = -10V, I <sub>D</sub> = -540mA	0.8			S
<b>Dynamic Characteristics(note 4)</b>						
Input Capacitance	C <sub>iss</sub>	V <sub>DS</sub> = -16V, V <sub>GS</sub> = 0V, f = 1MHz			170	pF
Output Capacitance	C <sub>oss</sub>				25	
Reverse Transfer Capacitance	C <sub>rss</sub>				15	
<b>Switching Times (note 4)</b>						
Turn-On Delay Time	t <sub>d(on)</sub>	V <sub>DD</sub> = -10V, I <sub>D</sub> = -200mA, V <sub>GS</sub> = -4.5V, R <sub>G</sub> = 10Ω		9		ns
Rise Time	t <sub>r</sub>			5.8		
Turn-Off Delay Time	t <sub>d(off)</sub>			32.7		
Fall Time	t <sub>f</sub>			20.3		
<b>Drain- Source Diode Characteristics</b>						
Drain-Source Diode Forward Voltage (note 3)	V <sub>SD</sub>	I <sub>S</sub> = -0.5A, V <sub>GS</sub> = 0V			-1.2	V

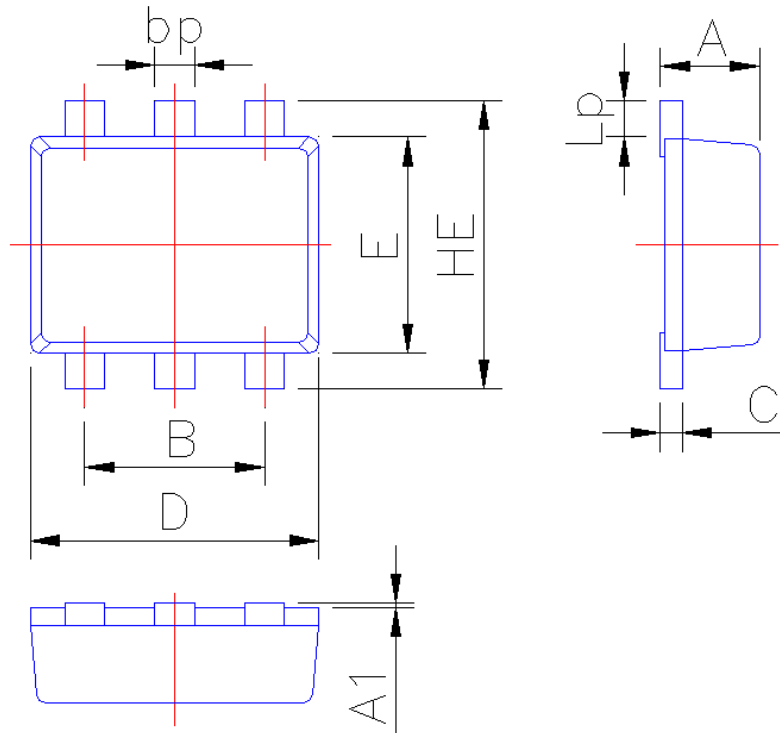
### Notes:

1. Repetitive Rating: Pulse width limited by maximum junction temperature.
2. This test is performed with no heat sink at T<sub>a</sub> = 25°C.
3. Pulse Test : Pulse Width ≤ 300μs, Duty Cycle ≤ 0.5%.
4. These parameters have no way to verify.

## Typical Characteristics



## SOT-563-Package Outline Dimensions



Symbol	Dimension in Millimeters	
	Min	Max
A	0.50	0.60
A1	0	0.05
B	0.95	1.05
bp	0.13	0.30
C	0.09	0.150
D	1.50	1.70
E	1.15	1.35
HE	1.40	1.80
Lp	0.13	0.30